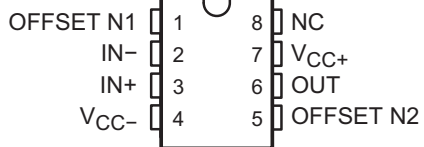


TL071, TL071A, TL071B, TL072 TL072A, TL072B, TL074, TL074A, TL074B

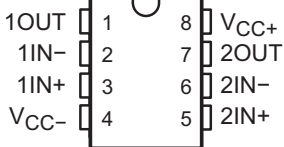
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS

SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

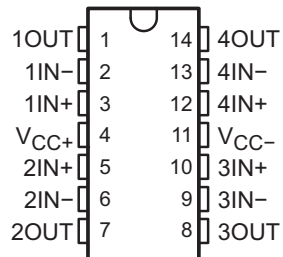
TL071, TL071A, TL071B
D, P, OR PS PACKAGE
(TOP VIEW)



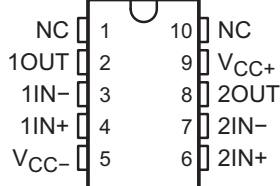
TL072, TL072A, TL072B
D, JG, P, PS, OR PW PACKAGE
(TOP VIEW)



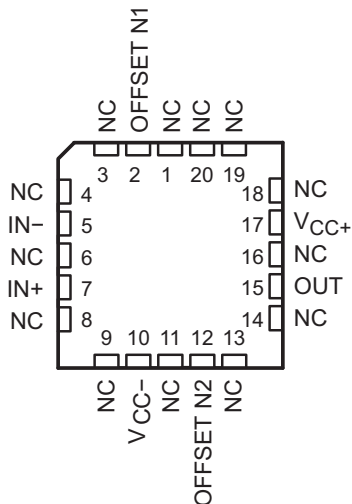
TL074A, TL074B
D, J, N, NS, OR PW PACKAGE
TL074 . . . D, J, N, NS, PW,
OR W PACKAGE
(TOP VIEW)



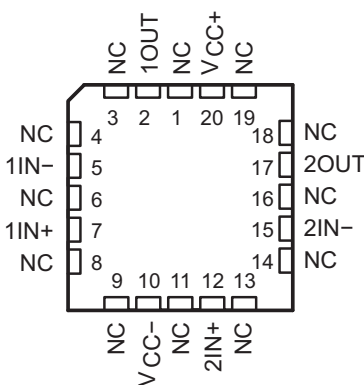
TL072
U PACKAGE
(TOP VIEW)



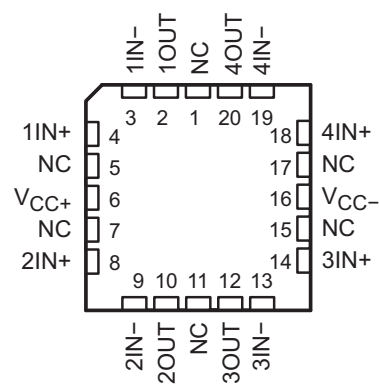
TL071
FK PACKAGE
(TOP VIEW)



TL072
FK PACKAGE
(TOP VIEW)

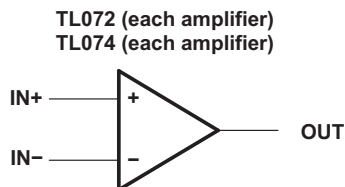
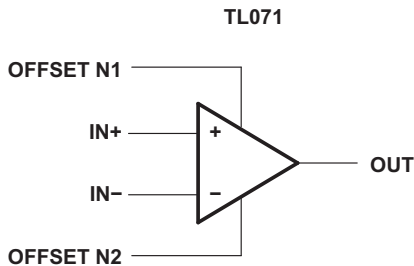


TL074
FK PACKAGE
(TOP VIEW)



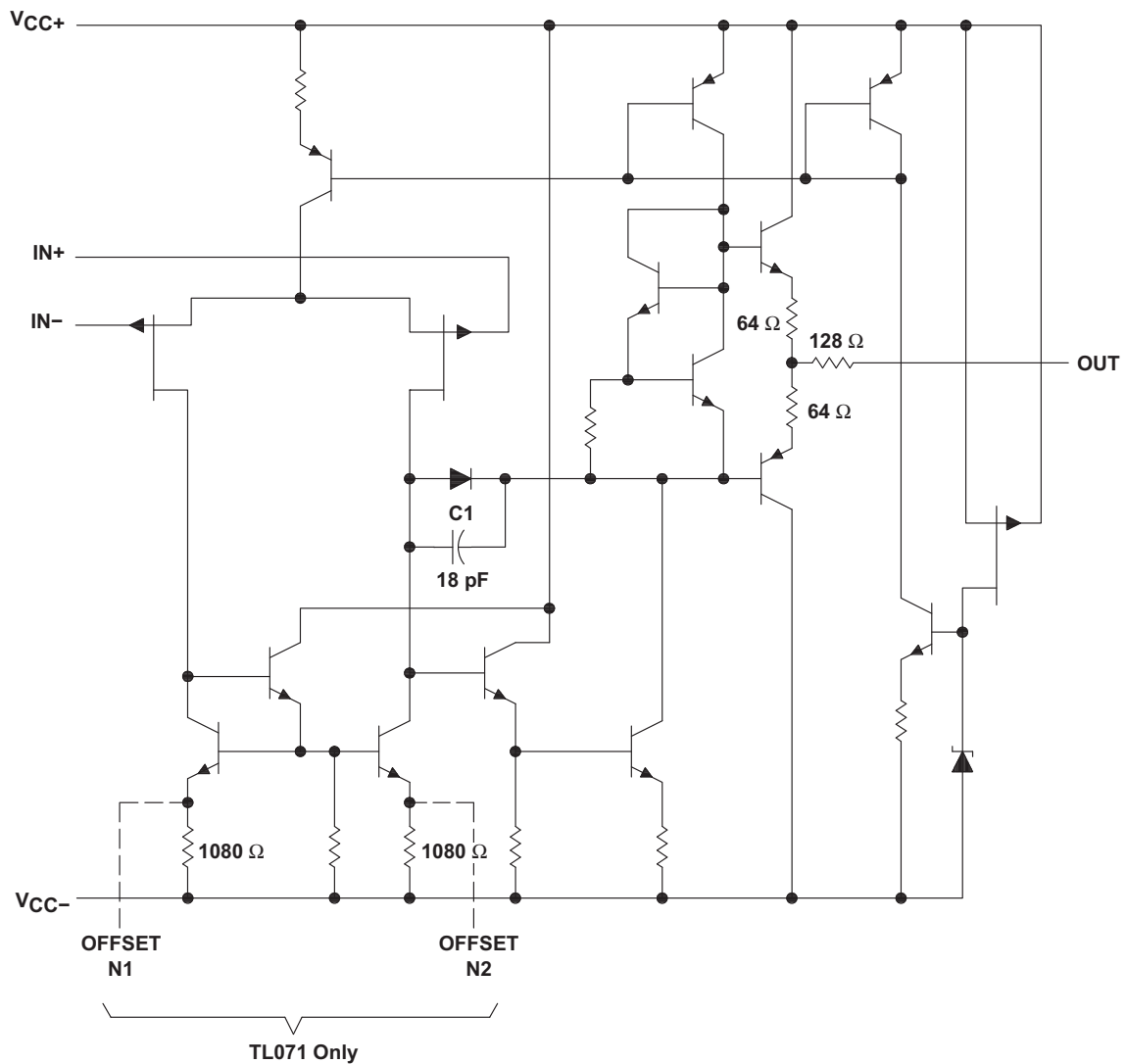
NC – No internal connection

symbols



TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS
SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

schematic (each amplifier)



All component values shown are nominal.

COMPONENT COUNT†			
COMPONENT TYPE	TL071	TL072	TL074
Resistors	11	22	44
Transistors	14	28	56
JFET	2	4	6
Diodes	1	2	4
Capacitors	1	2	4
epi-FET	1	2	4

† Includes bias and trim circuitry

TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS
 SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V_{CC+}	18 V
V_{CC-}	-18 V
Differential input voltage, V_{ID} (see Note 2)	± 30 V
Input voltage, V_I (see Notes 1 and 3)	± 15 V
Duration of output short circuit (see Note 4)	Unlimited
Package thermal impedance, θ_{JA} (see Notes 5 and 6): D package (8 pin)	97°C/W
D package (14 pin)	86°C/W
N package	80°C/W
NS package	76°C/W
P package	85°C/W
PS package	95°C/W
PW package (8 pin)	149°C/W
PW package (14 pin)	113°C/W
U package	185°C/W
Package thermal impedance, θ_{JC} (see Notes 7 and 8): FK package	5.61°C/W
J package	15.05°C/W
JG package	14.5°C/W
W package	14.65°C/W
Operating virtual junction temperature, T_J	150°C
Case temperature for 60 seconds: FK package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: J, JG, or W package	300°C
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-} .
 2. Differential voltages are at $IN+$, with respect to $IN-$.
 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 4. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 5. Maximum power dissipation is a function of $T_J(\max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 7. Maximum power dissipation is a function of $T_J(\max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(\max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 8. The package thermal impedance is calculated in accordance with MIL-STD-883.



**TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B**

SLOS080J - SEPTEMBER 1978 - REVISED MARCH 2005

electrical characteristics, $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	TA‡	TL071C TL072C TL074C			TL071AC TL072AC TL074AC			TL071BC TL072BC TL074BC			TL071I TL072I TL074I			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V _{IO}	V _O = 0, R _S = 50 Ω	25°C	3	10	6	3	6	3	6	3	6	3	6	mV	
		Full range		13	7.5		5	8							
αV_{IO}	V _O = 0, R _S = 50 Ω	Full range	18		18		18		18		18		18	$\mu\text{V}/^\circ\text{C}$	
		25°C	5	100	5	100	5	100	5	100	5	100	5	pA	
I _{IO}	V _O = 0	Full range	10		2		2		2		2		nA		
I _{IB}	V _O = 0	25°C	65	200	65	200	65	200	65	200	65	200	65	pA	
		Full range	7		7		7		7		7		20	nA	
V _{ICR}	Common-mode input voltage range	25°C	-12 to 15		-12 to 15		-12 to 15		-12 to 15		-12 to 15		-12 to 15	V	
		Full range	± 11		± 12		± 12		± 12		± 12		± 12		
V _{OM}	Maximum peak output voltage swing	25°C	± 12		± 12		± 12		± 12		± 12		± 12	V	
		Full range	± 10		± 10		± 10		± 10		± 10		± 10		
		25°C	25	200	25	200	25	200	25	200	25	200	25	V/mV	
A _{VD}	Large-signal differential voltage amplification	25°C	15		25		25		25		25		25	MHz	
		Full range	3		3		3		3		3		3		
B ₁	Unity-gain bandwidth	25°C	10 ¹²		10 ¹²		10 ¹²		10 ¹²		10 ¹²		10 ¹²	Ω	
CMRR	Common-mode rejection ratio	25°C	70	100	70	100	70	100	70	100	70	100	70	dB	
		Full range	70	100	70	100	70	100	70	100	70	100	70	dB	
k _{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	25°C	70	100	70	100	70	100	70	100	70	100	70	dB	
I _{CC}	Supply current (each amplifier)	25°C	1.4	2.5	1.4	2.5	1.4	2.5	1.4	2.5	1.4	2.5	1.4	2.5	mA
V _{O1} /V _{O2}	Crosstalk attenuation	25°C	120		120		120		120		120		120	dB	

† All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified.

‡ Full range is T_A = 0°C to 70°C for TL07_C, TL07_AC, TL07_BC and is T_A = -40°C to 85°C for TL07_I.

§ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 4. Pulse techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.



TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS
 SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

electrical characteristics, $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	T_A ‡	TL071M TL072M			TL074M			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_O = 0, R_S = 50\ \Omega$	25°C	3	6		3	9	mV	
		Full range			9		15		
αV_{IO} Temperature coefficient of input offset voltage	$V_O = 0, R_S = 50\ \Omega$	Full range	18			18			$\mu\text{V}/^\circ\text{C}$
I_{IO} Input offset current	$V_O = 0$	25°C	5	100		5	100	pA	
		Full range	20			20			nA
I_{IB} Input bias current‡	$V_O = 0$	25°C	65	200		65	200	pA	
		Full range	50			50			nA
V_{ICR} Common-mode input voltage range		25°C	± 11	-12 to 15		± 11	-12 to 15	V	
V_{OM} Maximum peak output voltage swing	$R_L = 10\ \text{k}\Omega$	25°C	± 12	± 13.5		± 12	± 13.5	V	
	$R_L \geq 10\ \text{k}\Omega$	Full range	± 12			± 12			
	$R_L \geq 2\ \text{k}\Omega$		± 10			± 10			
A_{VD} Large-signal differential voltage amplification	$V_O = \pm 10\ \text{V}, R_L \geq 2\ \text{k}\Omega$	25°C	35	200		35	200	V/mV	
		Full range	15			15			
B_1 Unity-gain bandwidth	$T_A = 25^\circ\text{C}$		3			3			MHz
r_i Input resistance	$T_A = 25^\circ\text{C}$		10^{12}			10^{12}			Ω
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}, V_O = 0, R_S = 50\ \Omega$	25°C	80	86		80	86	dB	
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC} = \pm 9\ \text{V to } \pm 15\ \text{V}, V_O = 0, R_S = 50\ \Omega$	25°C	80	86		80	86	dB	
I_{CC} Supply current (each amplifier)	$V_O = 0, \text{ No load}$	25°C	1.4	2.5		1.4	2.5	mA	
V_{O1}/V_{O2} Crosstalk attenuation	$A_{VD} = 100$	25°C	120			120			dB

† Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 4. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

‡ All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range is $T_A = -55^\circ\text{C to } 125^\circ\text{C}$.

TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS
SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

operating characteristics, $V_{CC\pm} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TL07xM			ALL OTHERS			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
SR	Slew rate at unity gain $V_I = 10\text{ V}$, $C_L = 100\text{ pF}$, $R_L = 2\text{ k}\Omega$, See Figure 1	5	13		8	13		$\text{V}/\mu\text{s}$
t_r	Rise-time overshoot factor $V_I = 20\text{ mV}$, $C_L = 100\text{ pF}$, $R_L = 2\text{ k}\Omega$, See Figure 1	0.1			0.1			μs
		20%			20%			
V_n	Equivalent input noise voltage $R_S = 20\ \Omega$	$f = 1\text{ kHz}$			18			$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ Hz to } 10\text{ kHz}$			4			μV
I_n	Equivalent input noise current $R_S = 20\ \Omega$, $f = 1\text{ kHz}$	0.01			0.01			$\text{pA}/\sqrt{\text{Hz}}$
THD	Total harmonic distortion $V_{I\text{rms}} = 6\text{ V}$, $R_L \geq 2\text{ k}\Omega$, $f = 1\text{ kHz}$	0.003 %			0.003%			

PARAMETER MEASUREMENT INFORMATION

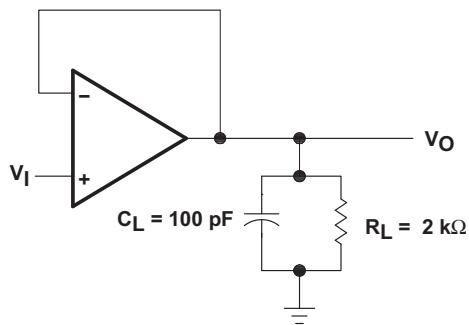


Figure 1. Unity-Gain Amplifier

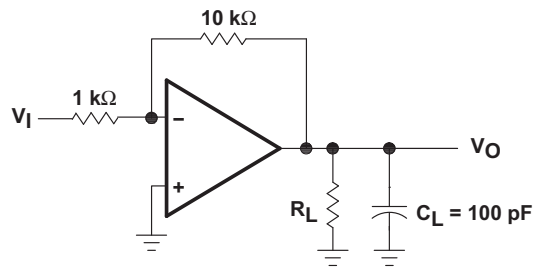


Figure 2. Gain-of-10 Inverting Amplifier

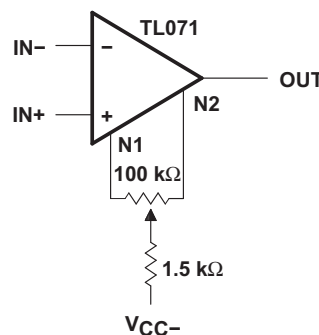


Figure 3. Input Offset-Voltage Null Circuit

TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS
 SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

TYPICAL CHARACTERISTICS

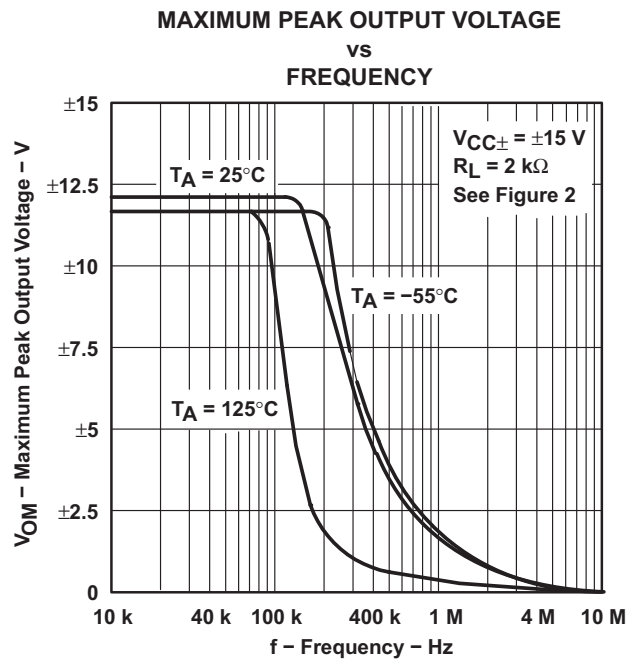
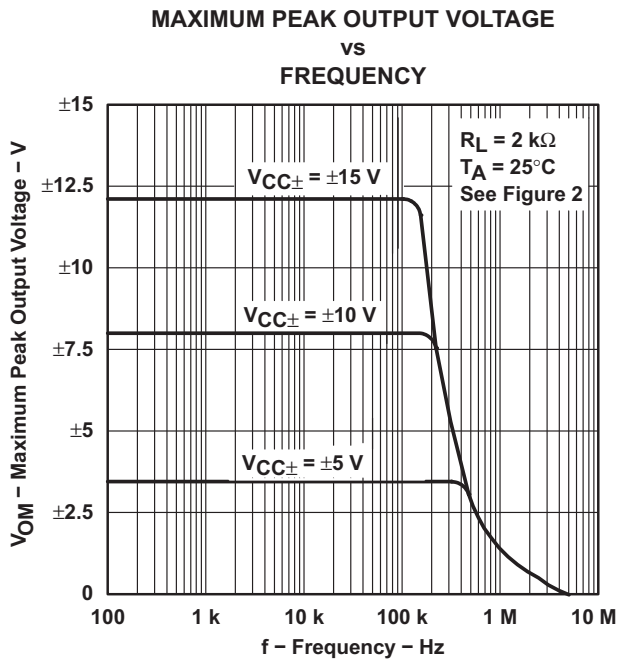
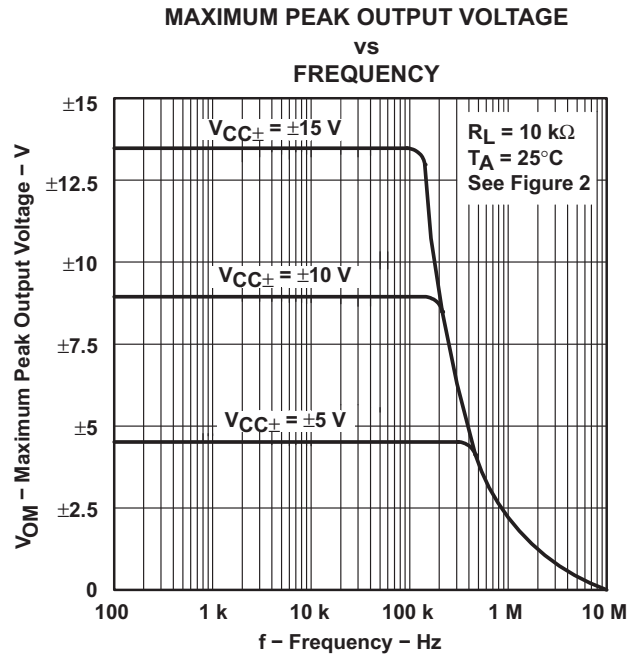
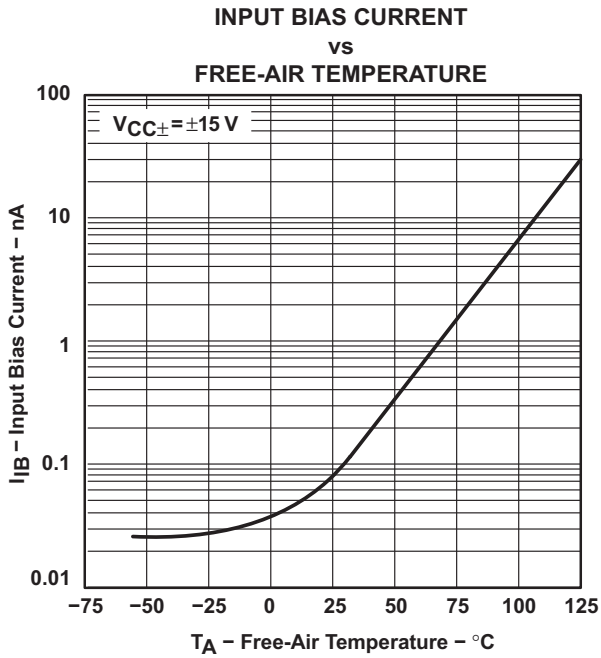
Table of Graphs

			FIGURE
I_{IB}	Input bias current	vs Free-air temperature	4
V_{OM}	Maximum output voltage	vs Frequency	5, 6, 7
		vs Free-air temperature	8
		vs Load resistance	9
		vs Supply voltage	10
A_{VD}	Large-signal differential voltage amplification	vs Free-air temperature	11
		vs Frequency	12
	Phase shift	vs Frequency	12
	Normalized unity-gain bandwidth	vs Free-air temperature	13
	Normalized phase shift	vs Free-air temperature	13
$CMRR$	Common-mode rejection ratio	vs Free-air temperature	14
I_{CC}	Supply current	vs Supply voltage	15
		vs Free-air temperature	16
P_D	Total power dissipation	vs Free-air temperature	17
		Normalized slew rate	vs Free-air temperature
V_n	Equivalent input noise voltage	vs Frequency	19
THD	Total harmonic distortion	vs Frequency	20
		Large-signal pulse response	vs Time
V_O	Output voltage	vs Elapsed time	22



TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS
SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

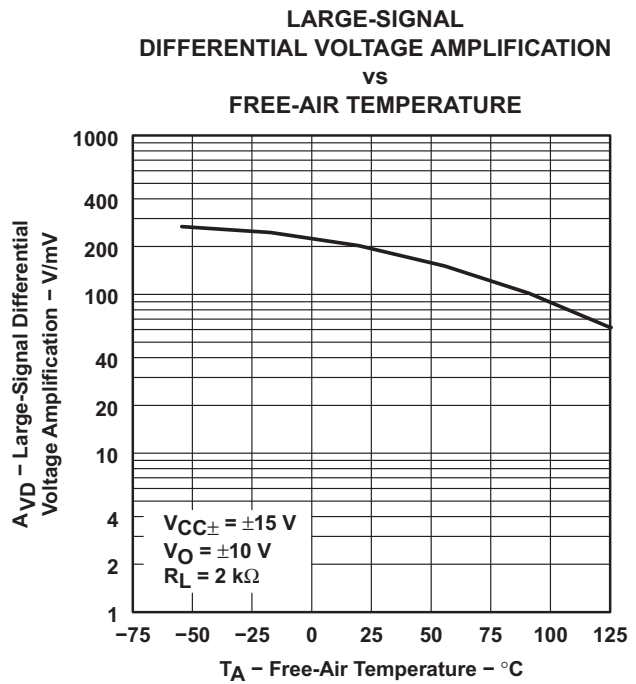
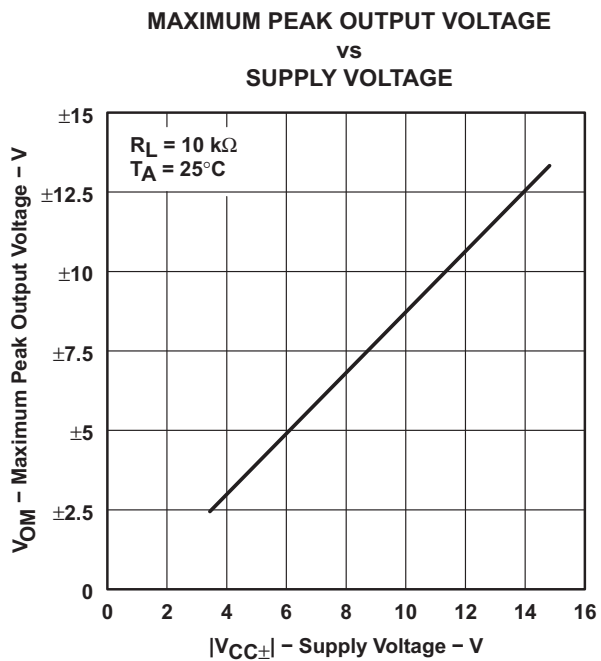
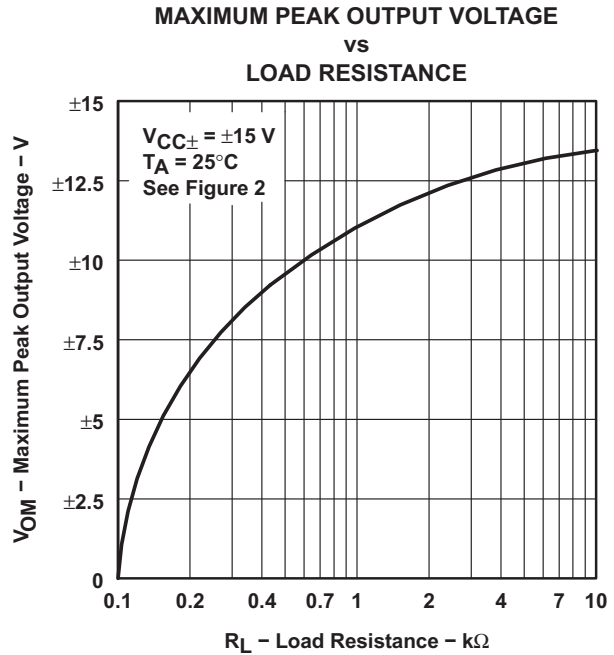
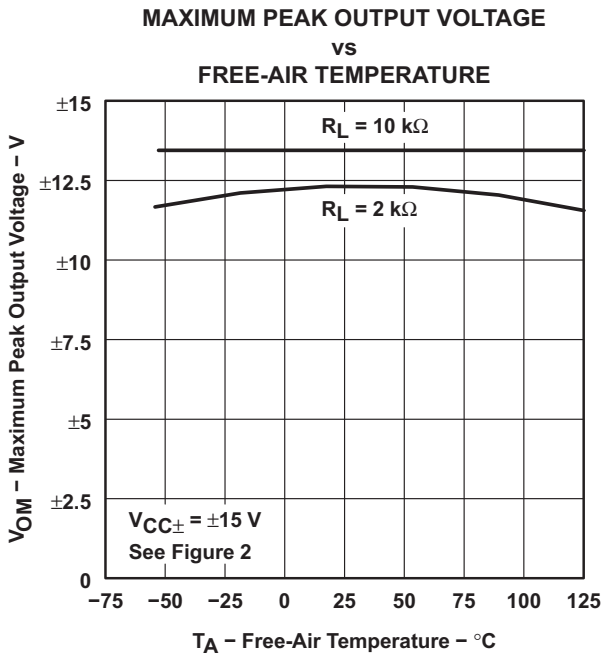
TYPICAL CHARACTERISTICS†



† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS
 SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

TYPICAL CHARACTERISTICS†



† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

**LARGE-SIGNAL
 DIFFERENTIAL VOLTAGE AMPLIFICATION
 AND PHASE SHIFT
 vs
 FREQUENCY**

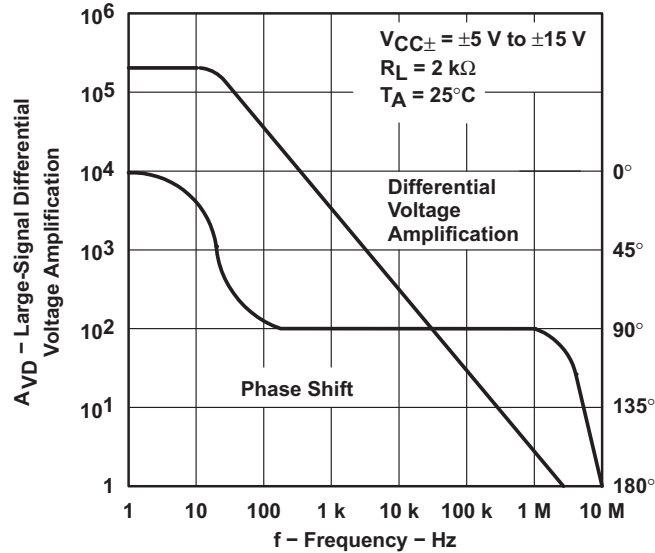


Figure 12

**NORMALIZED UNITY-GAIN BANDWIDTH
 AND PHASE SHIFT
 vs
 FREE-AIR TEMPERATURE**

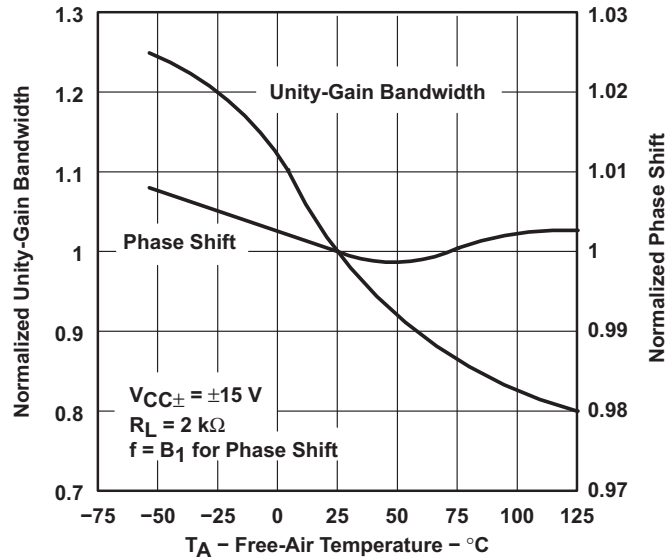


Figure 13

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS
 SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

TYPICAL CHARACTERISTICS†

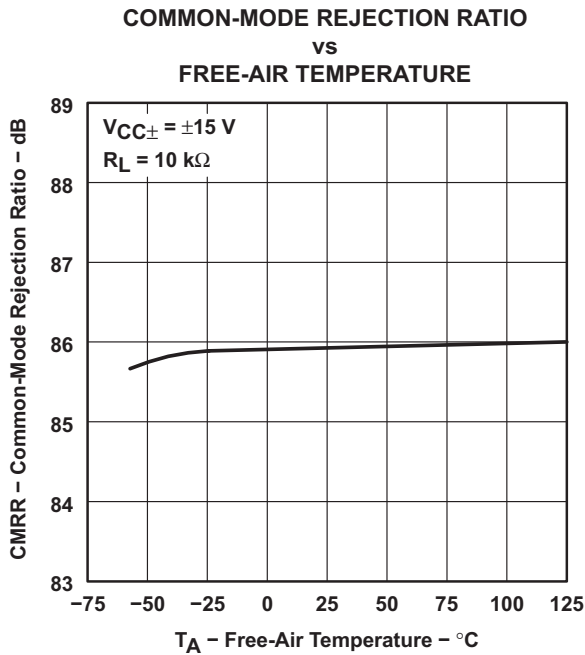


Figure 14

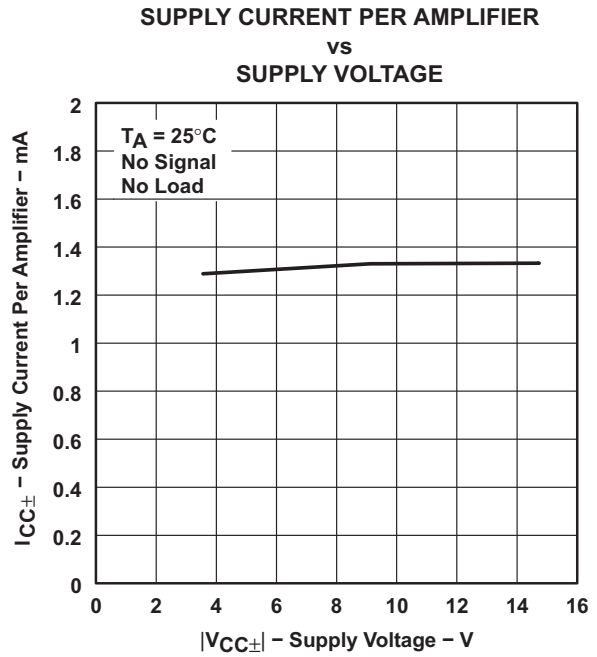


Figure 15

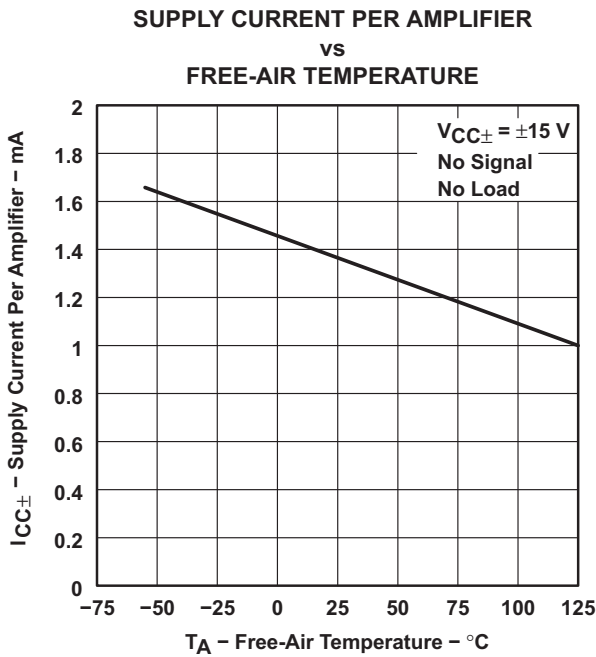


Figure 16

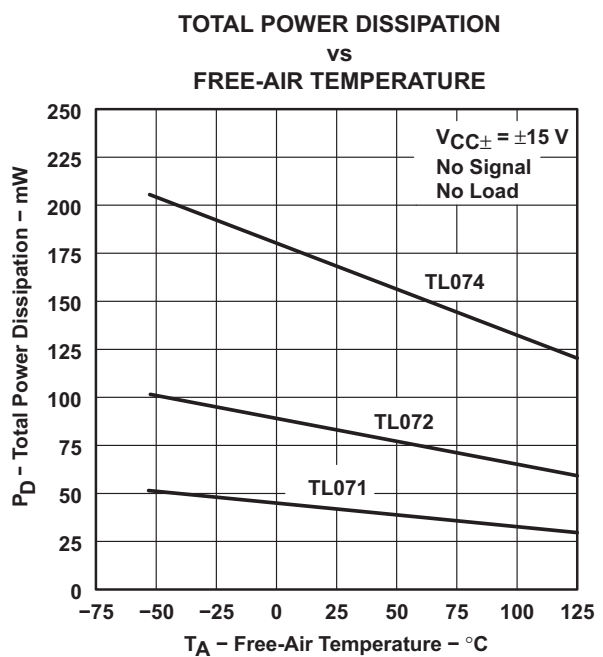
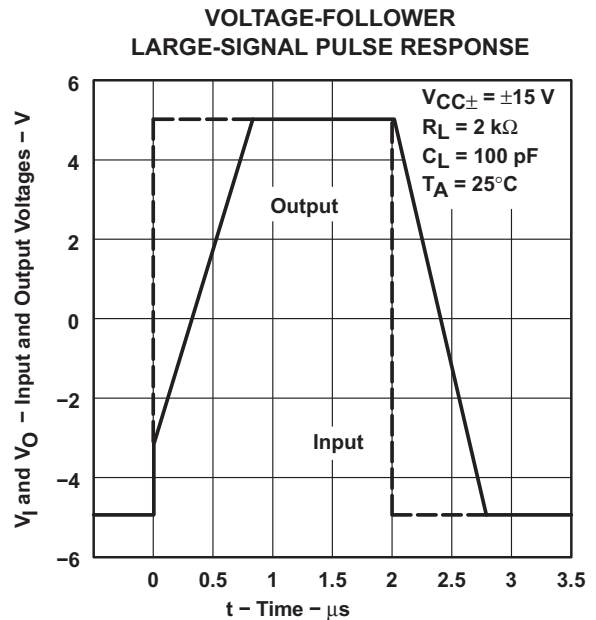
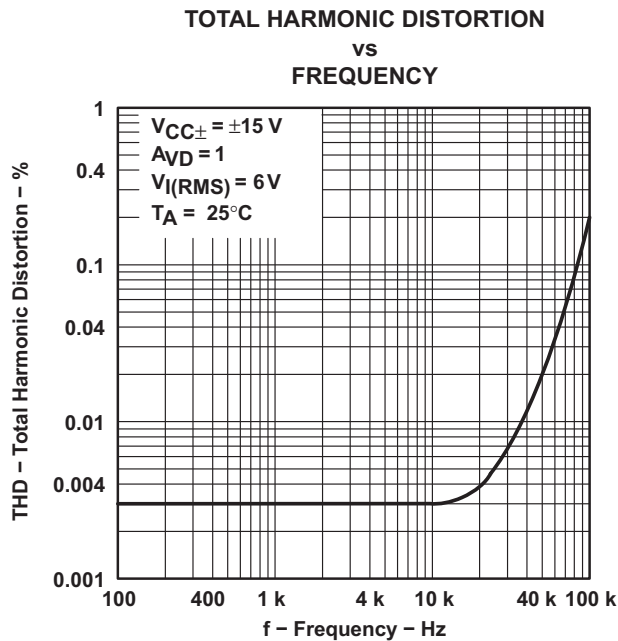
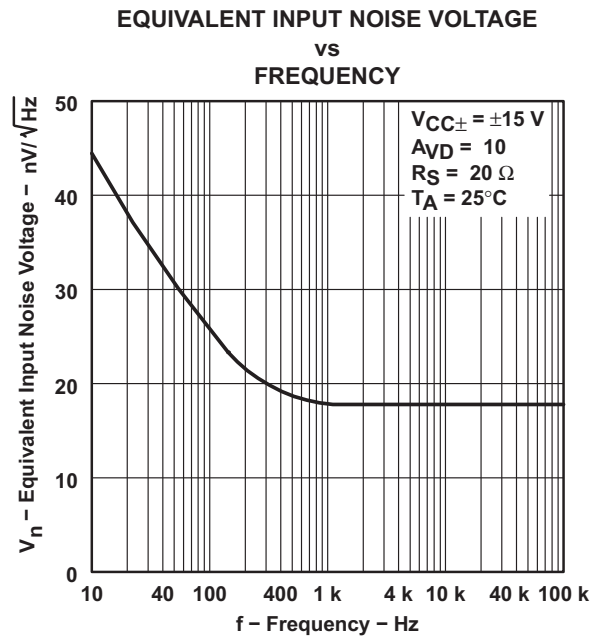
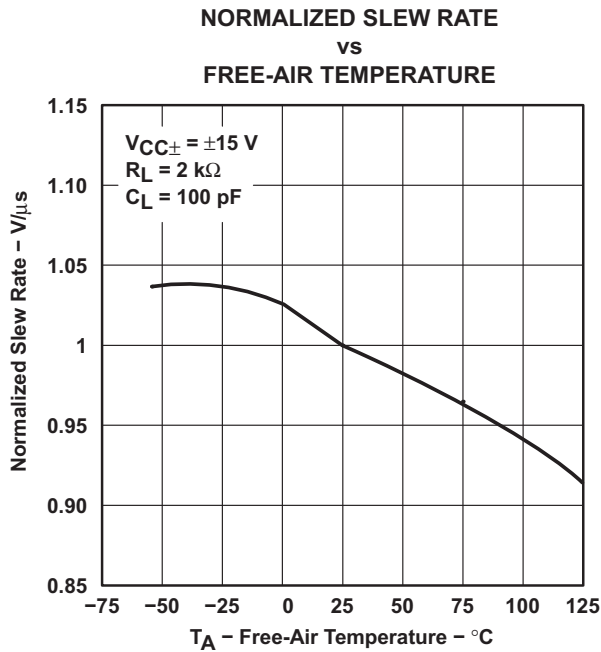


Figure 17

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

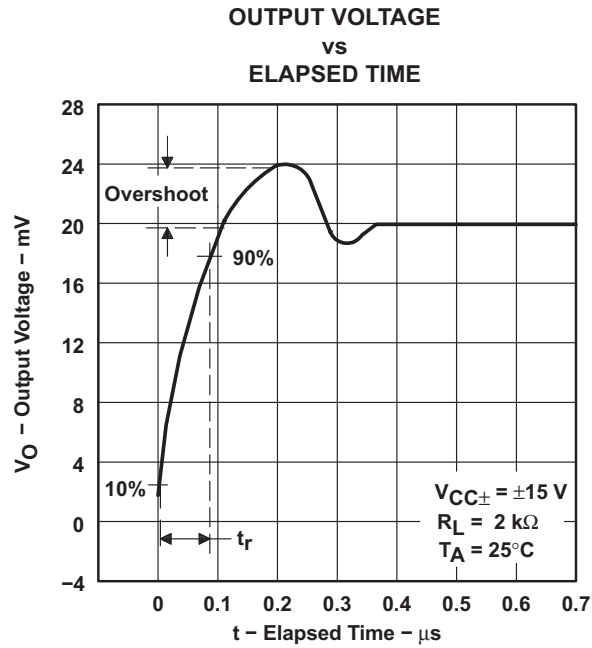


Figure 22

APPLICATION INFORMATION

Table of Application Diagrams

APPLICATION DIAGRAM	PART NUMBER	FIGURE
0.5-Hz square-wave oscillator	TL071	23
High-Q notch filter	TL071	24
Audio-distribution amplifier	TL074	25
100-kHz quadrature oscillator	TL072	26
AC amplifier	TL071	27

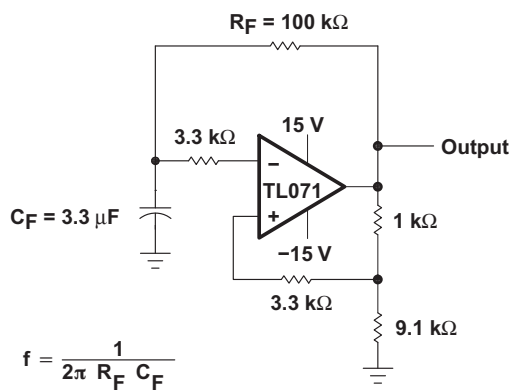


Figure 23. 0.5-Hz Square-Wave Oscillator

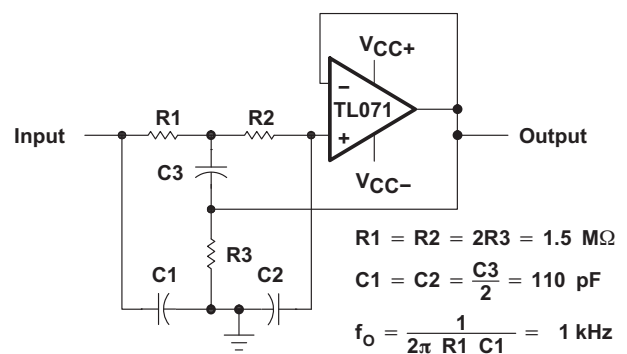


Figure 24. High-Q Notch Filter

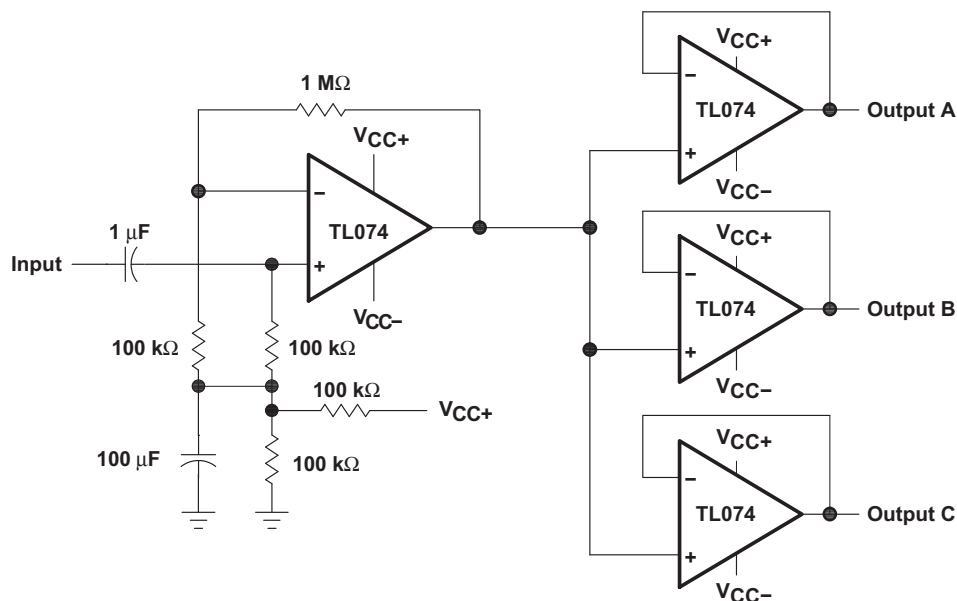
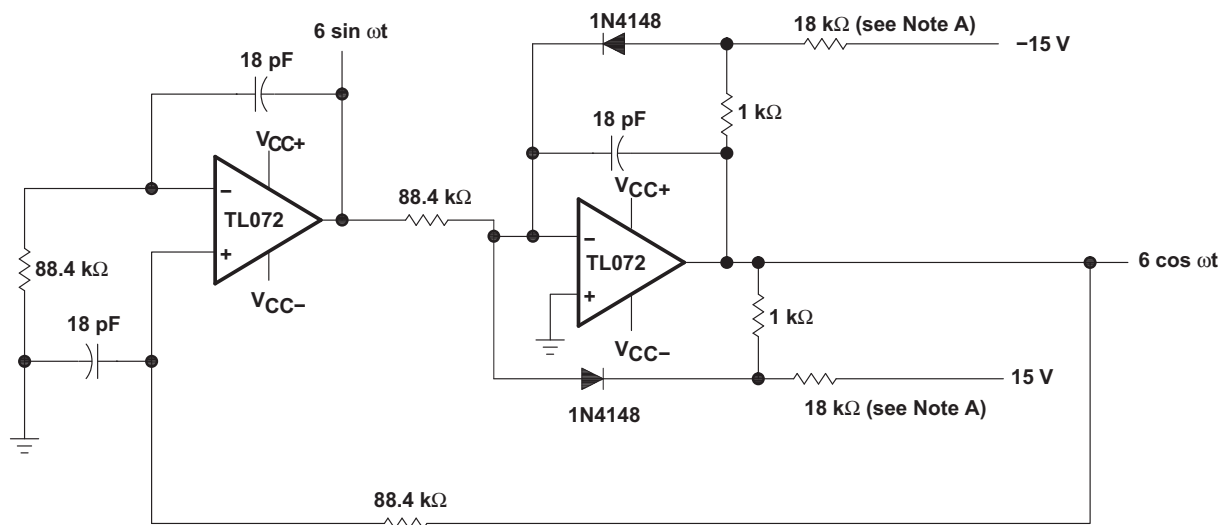


Figure 25. Audio-Distribution Amplifier

TL071, TL071A, TL071B, TL072
TL072A, TL072B, TL074, TL074A, TL074B
LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS

SLOS080J – SEPTEMBER 1978 – REVISED MARCH 2005

APPLICATION INFORMATION



NOTE A: These resistor values may be adjusted for a symmetrical output.

Figure 26. 100-kHz Quadrature Oscillator

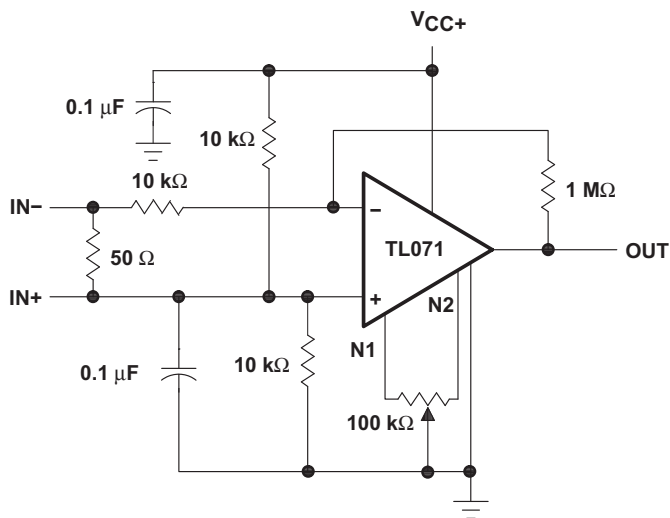


Figure 27. AC Amplifier

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
8102304HA	OBSOLETE			10		TBD	Call TI	Call TI
81023052A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8102305HA	ACTIVE	CFP	U	10	1	TBD	A42 SNPB	N / A for Pkg Type
8102305PA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
81023062A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8102306CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
8102306DA	ACTIVE	CFP	W	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/11905BPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/11906BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL071ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
TL071CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TL071ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL071IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL071MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL071MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL072ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL072ACP	ACTIVE	PDIP	P	8	50	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						(RoHS)		
TL072ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072CPSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI
TL072CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
TL072CPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL072MJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL072MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL072MUB	ACTIVE	CFP	U	10	1	TBD	A42 SNPB	N / A for Pkg Type
TL074ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL074ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074ACNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL074BCDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074BCNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074BCNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074CNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
TL074CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL074CPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL074IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074MFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL074MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL074MJ	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
TL074MJB	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
TL074MWB	ACTIVE	CFP	W	14	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

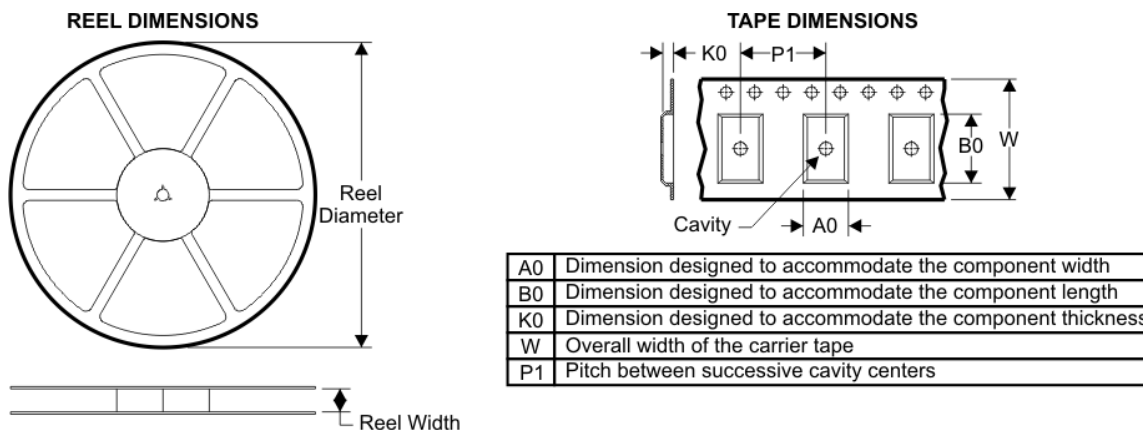
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

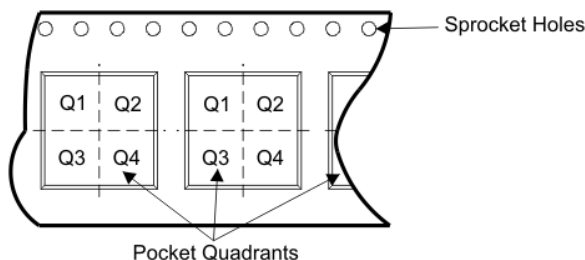
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TAPE AND REEL BOX INFORMATION



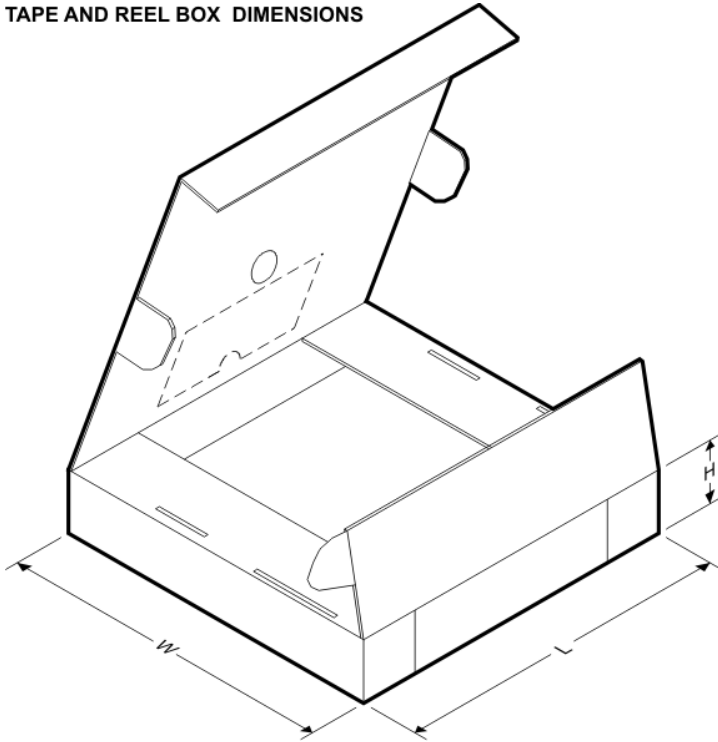
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL071ACDR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
TL071BCDR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
TL071CDR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
TL071CDR	D	8	SITE 41	330	12	6.4	5.2	2.1	8	12	Q1
TL071CPSR	PS	8	SITE 41	330	16	8.2	6.6	2.5	12	16	Q1
TL071IDR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
TL072ACDR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
TL072ACPSR	PS	8	SITE 41	330	16	8.2	6.6	2.5	12	16	Q1
TL072BCDR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
TL072CDR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
TL072CDR	D	8	SITE 41	330	12	6.4	5.2	2.1	8	12	Q1
TL072CPSR	PS	8	SITE 41	330	16	8.2	6.6	2.5	12	16	Q1
TL072CPWR	PW	8	SITE 41	330	12	7.0	3.6	1.6	8	12	Q1
TL072IDR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
TL072IDR	D	8	SITE 41	330	12	6.4	5.2	2.1	8	12	Q1
TL074ACDR	D	14	SITE 27	330	16	6.5	9.0	2.1	8	16	Q1
TL074ACNSR	NS	14	SITE 41	330	16	8.2	10.5	2.5	12	16	Q1
TL074BCDR	D	14	SITE 27	330	16	6.5	9.0	2.1	8	16	Q1
TL074BCNSR	NS	14	SITE 41	330	16	8.2	10.5	2.5	12	16	Q1

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL074CDR	D	14	SITE 27	330	16	6.5	9.0	2.1	8	16	Q1
TL074CNSR	NS	14	SITE 41	330	16	8.2	10.5	2.5	12	16	Q1
TL074CPWR	PW	14	SITE 41	330	12	7.0	5.6	1.6	8	12	Q1
TL074IDR	D	14	SITE 27	330	16	6.5	9.0	2.1	8	16	Q1

TAPE AND REEL BOX DIMENSIONS



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
TL071ACDR	D	8	SITE 27	342.9	336.6	20.64
TL071BCDR	D	8	SITE 27	342.9	336.6	20.64
TL071CDR	D	8	SITE 27	342.9	336.6	20.64
TL071CDR	D	8	SITE 41	346.0	346.0	29.0
TL071CPSR	PS	8	SITE 41	346.0	346.0	33.0
TL071IDR	D	8	SITE 27	342.9	336.6	20.64
TL072ACDR	D	8	SITE 27	342.9	336.6	20.64
TL072ACPSR	PS	8	SITE 41	346.0	346.0	33.0
TL072BCDR	D	8	SITE 27	342.9	336.6	20.64
TL072CDR	D	8	SITE 27	342.9	336.6	20.64
TL072CDR	D	8	SITE 41	346.0	346.0	29.0
TL072CPSR	PS	8	SITE 41	346.0	346.0	33.0
TL072CPWR	PW	8	SITE 41	346.0	346.0	29.0

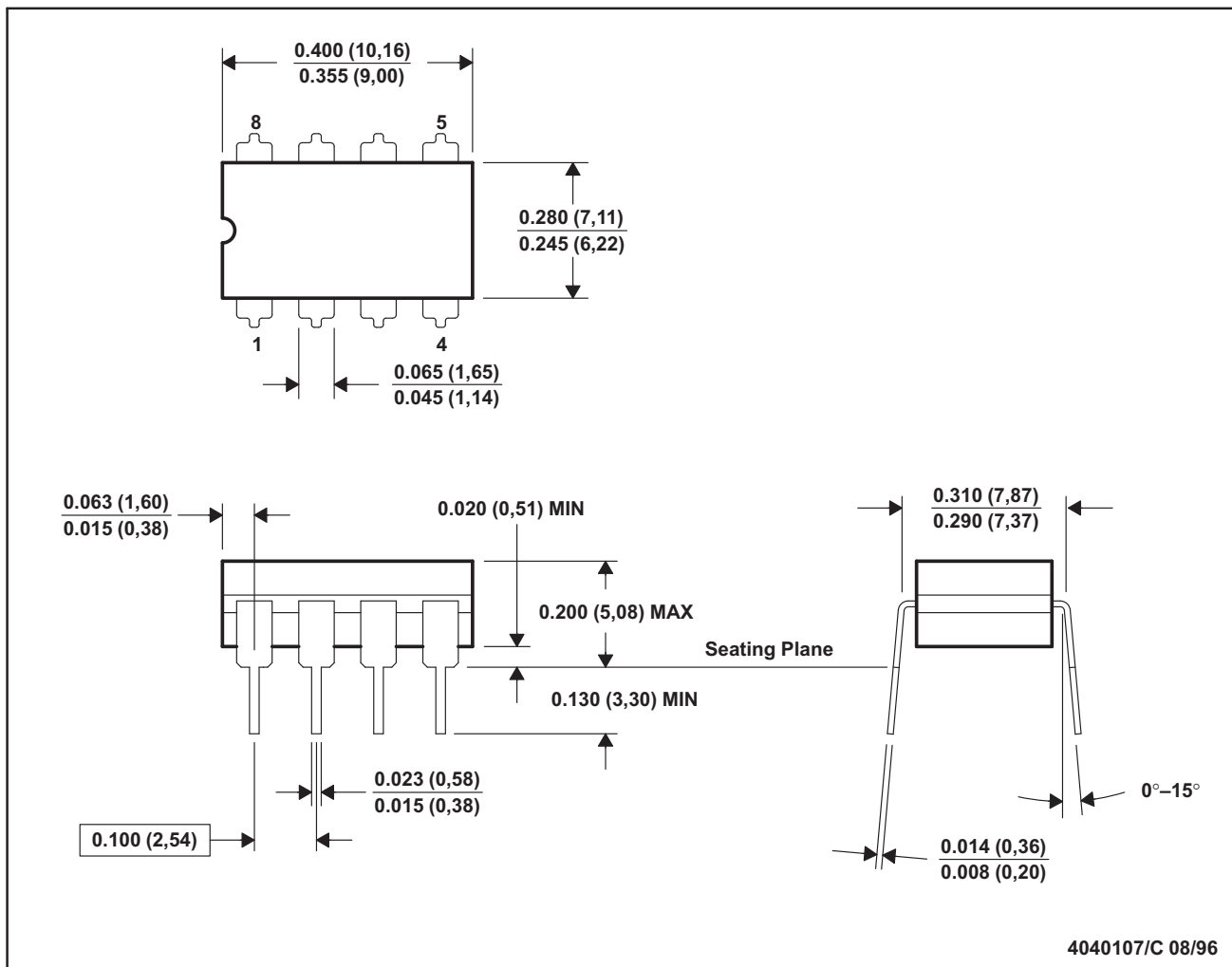
Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
TL072IDR	D	8	SITE 27	342.9	336.6	20.64
TL072IDR	D	8	SITE 41	346.0	346.0	29.0
TL074ACDR	D	14	SITE 27	342.9	336.6	28.58
TL074ACNSR	NS	14	SITE 41	346.0	346.0	33.0
TL074BCDR	D	14	SITE 27	342.9	336.6	28.58
TL074BCNSR	NS	14	SITE 41	346.0	346.0	33.0
TL074CDR	D	14	SITE 27	342.9	336.6	28.58
TL074CNSR	NS	14	SITE 41	346.0	346.0	33.0
TL074CPWR	PW	14	SITE 41	346.0	346.0	29.0
TL074IDR	D	14	SITE 27	342.9	336.6	28.58

MECHANICAL DATA

MCER001A – JANUARY 1995 – REVISED JANUARY 1997

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP1-T8

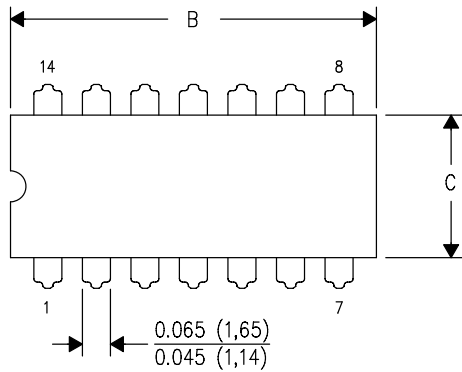
**TEXAS
INSTRUMENTS**

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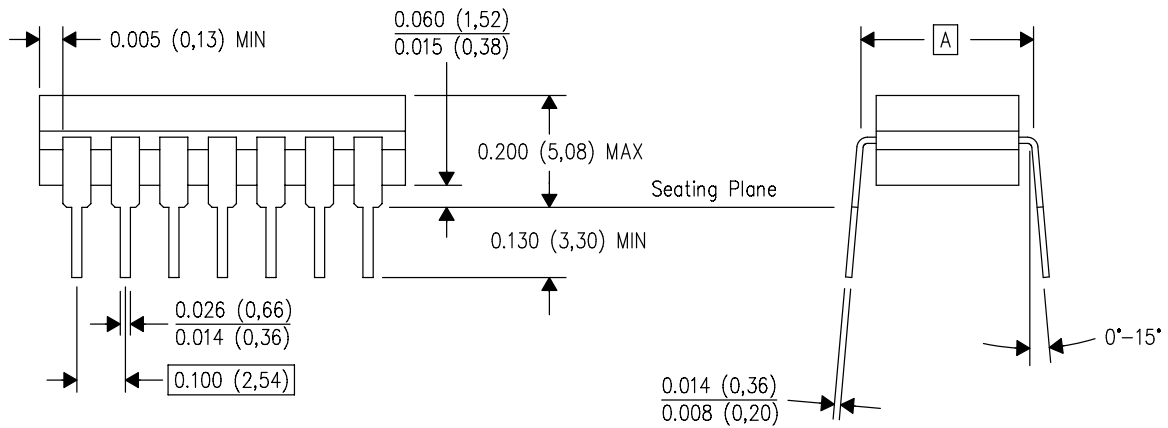
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



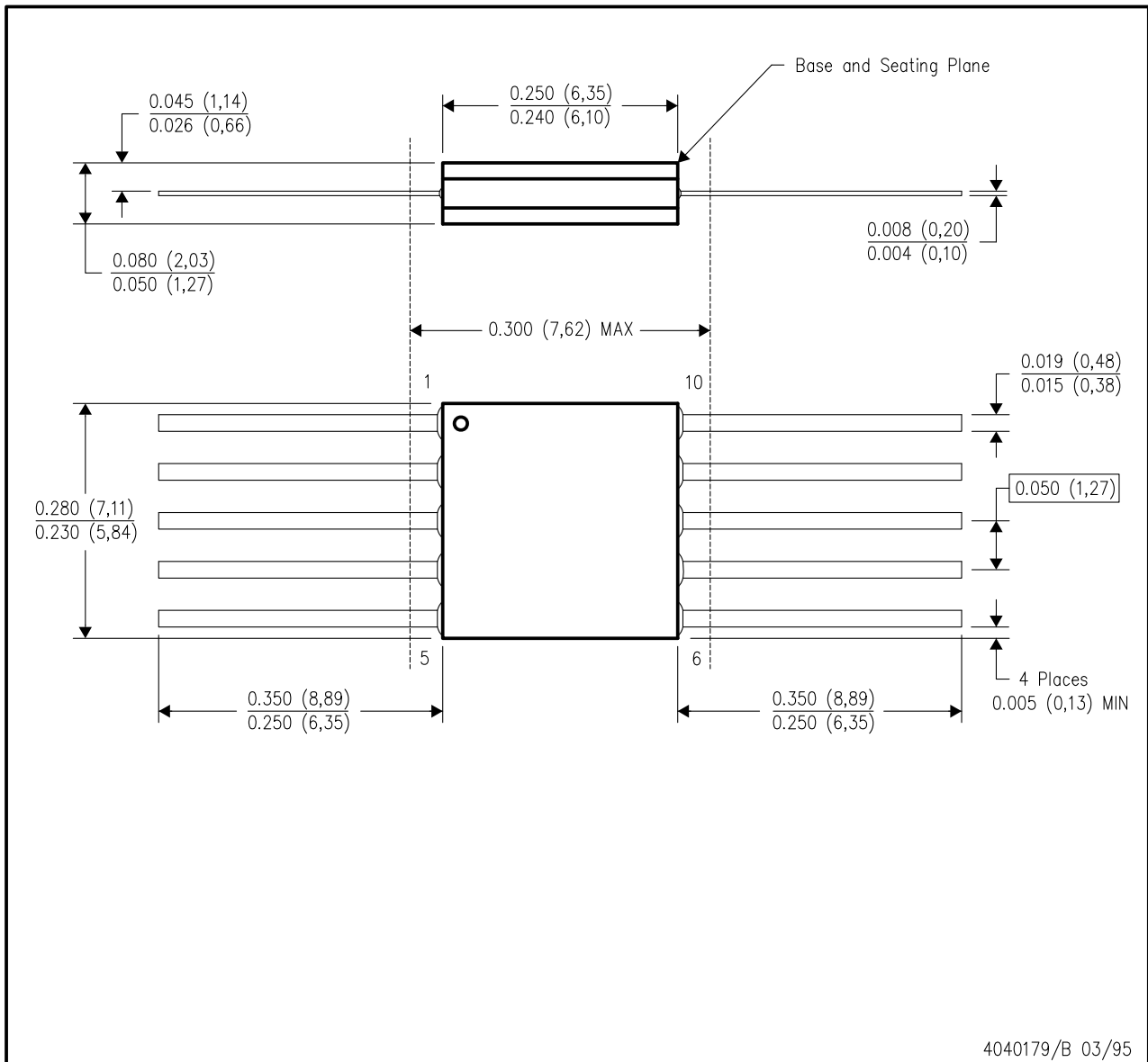
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

U (S-GDFP-F10)

CERAMIC DUAL FLATPACK

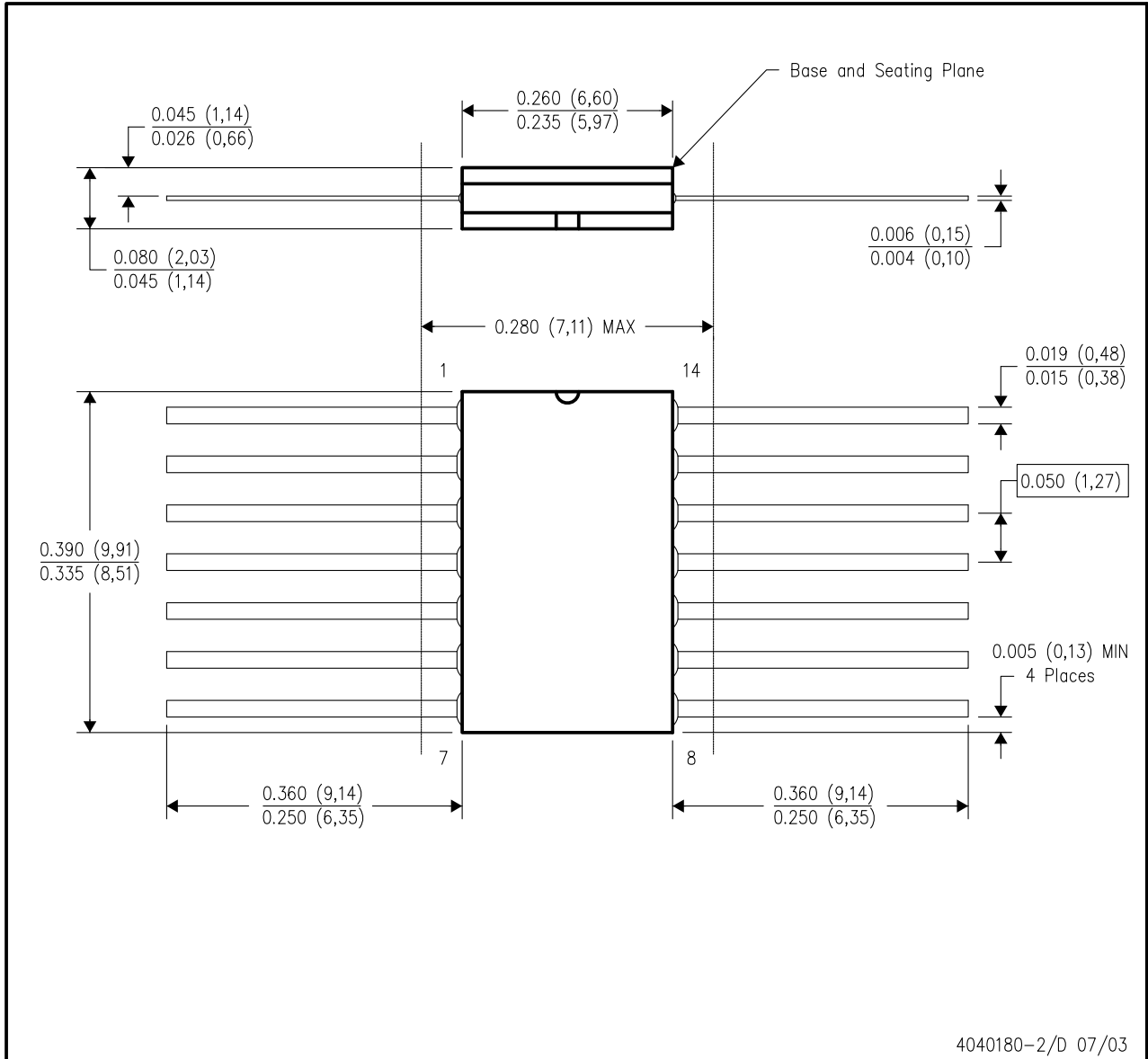


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



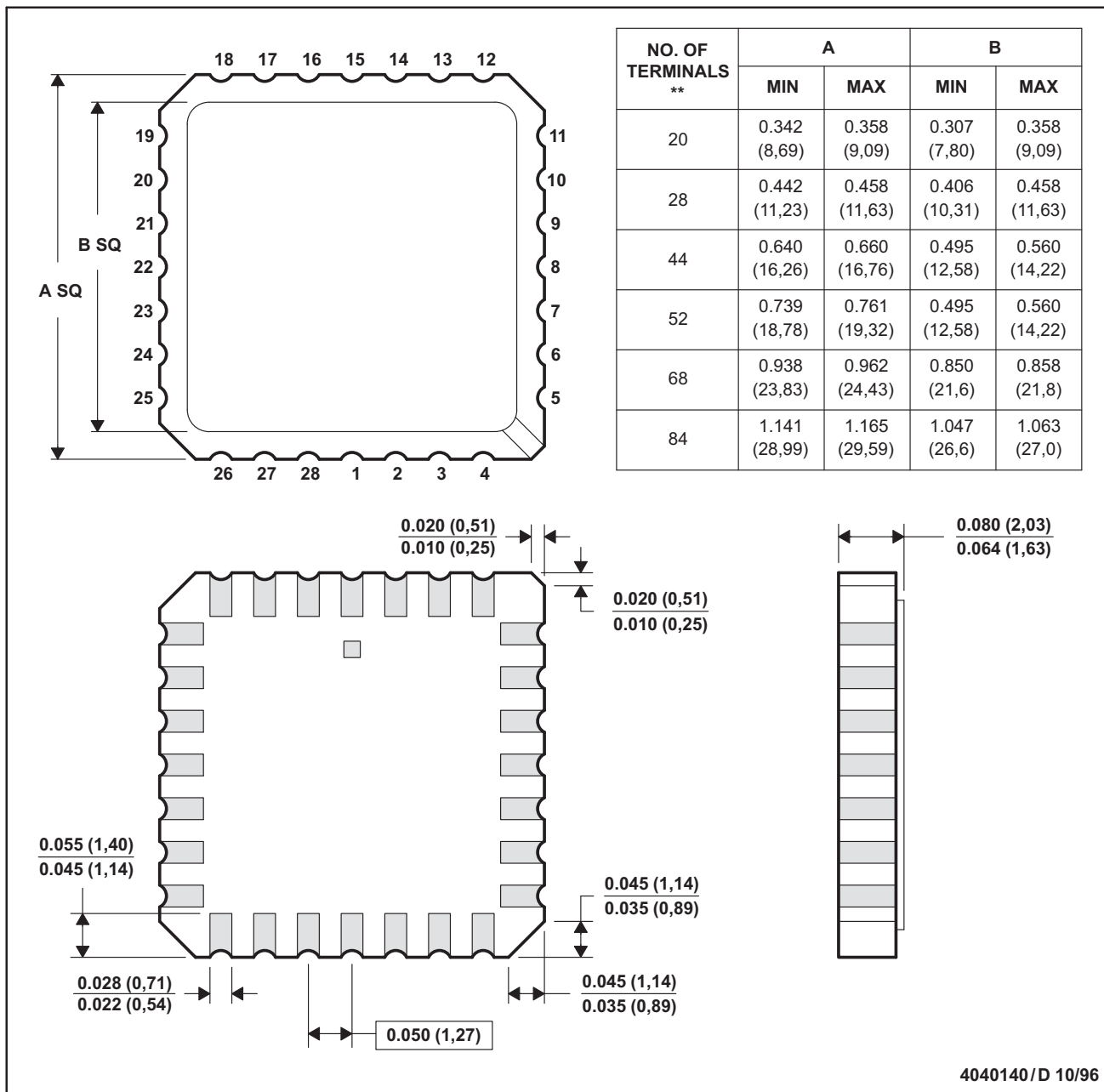
4040180-2/D 07/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

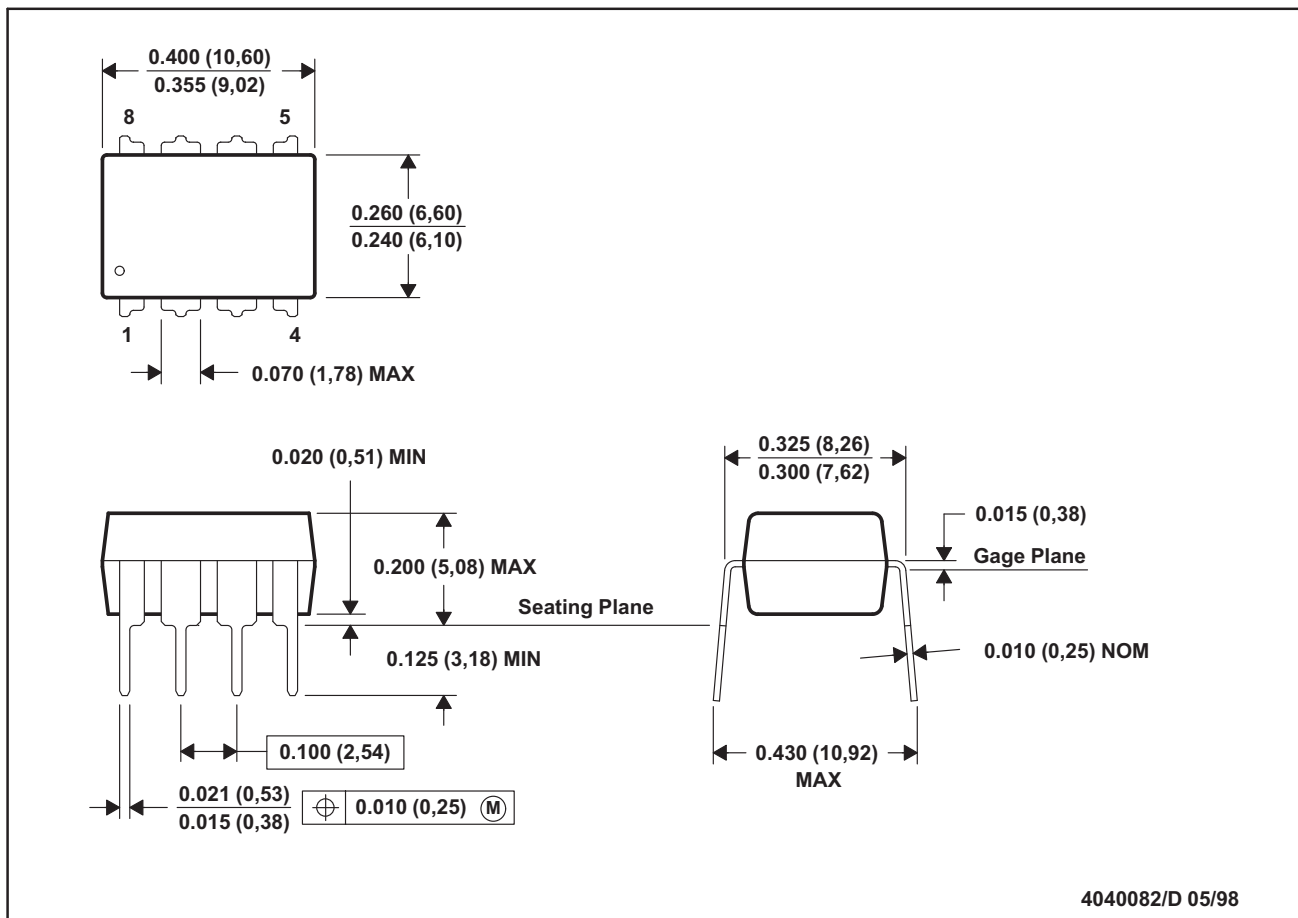
28 TERMINAL SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a metal lid.
 D. The terminals are gold plated.
 E. Falls within JEDEC MS-004

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm



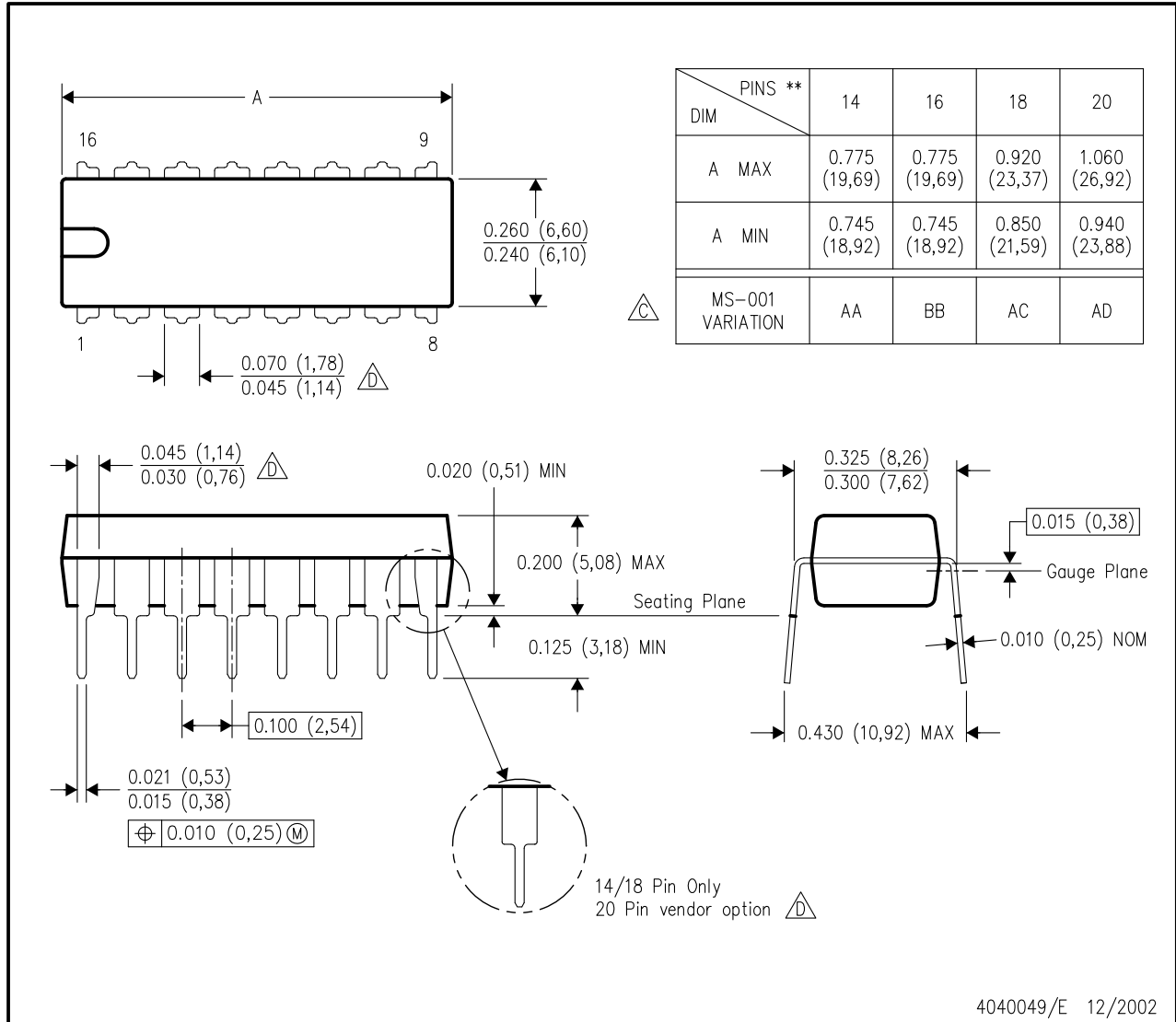
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MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

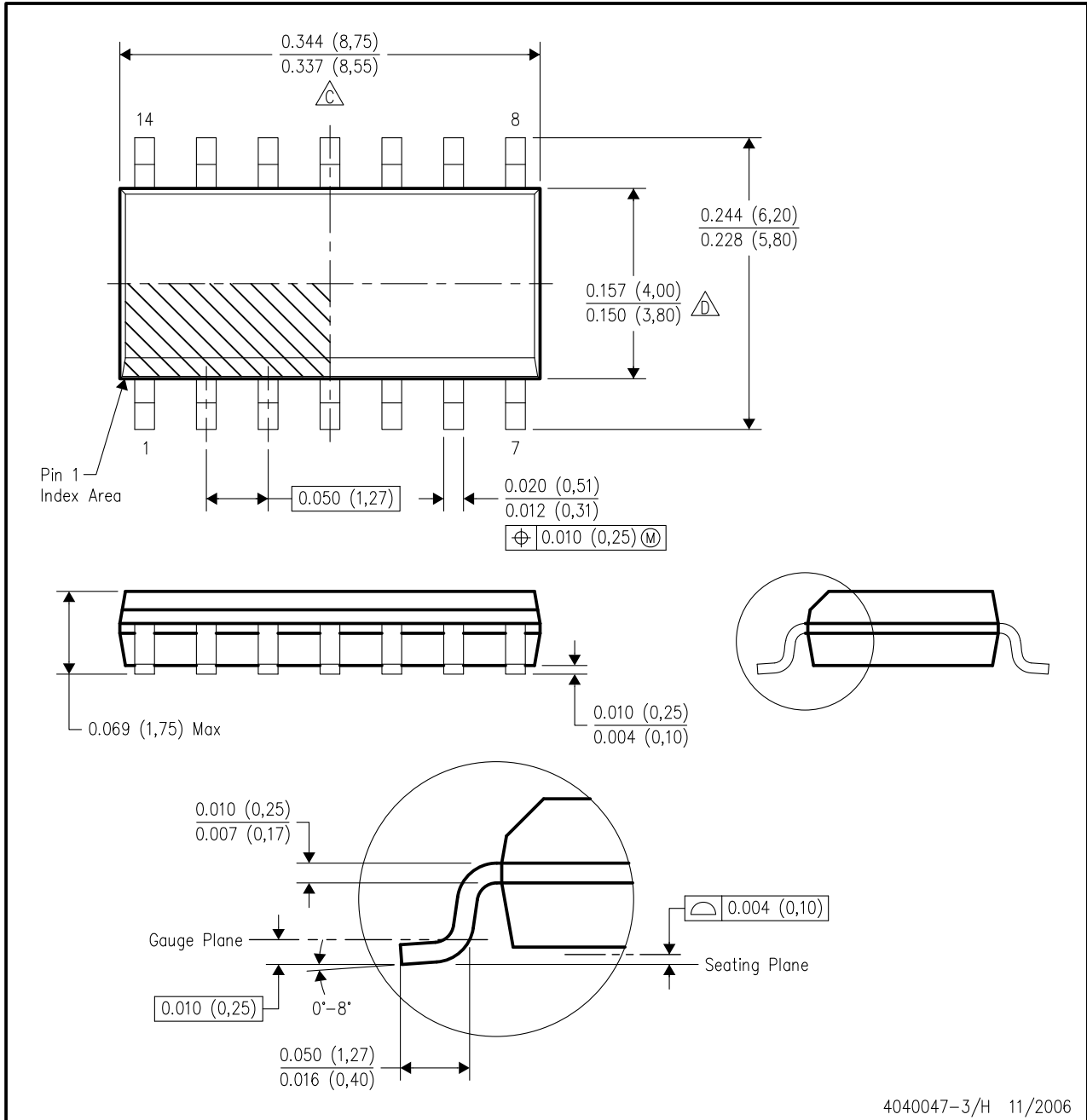
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE

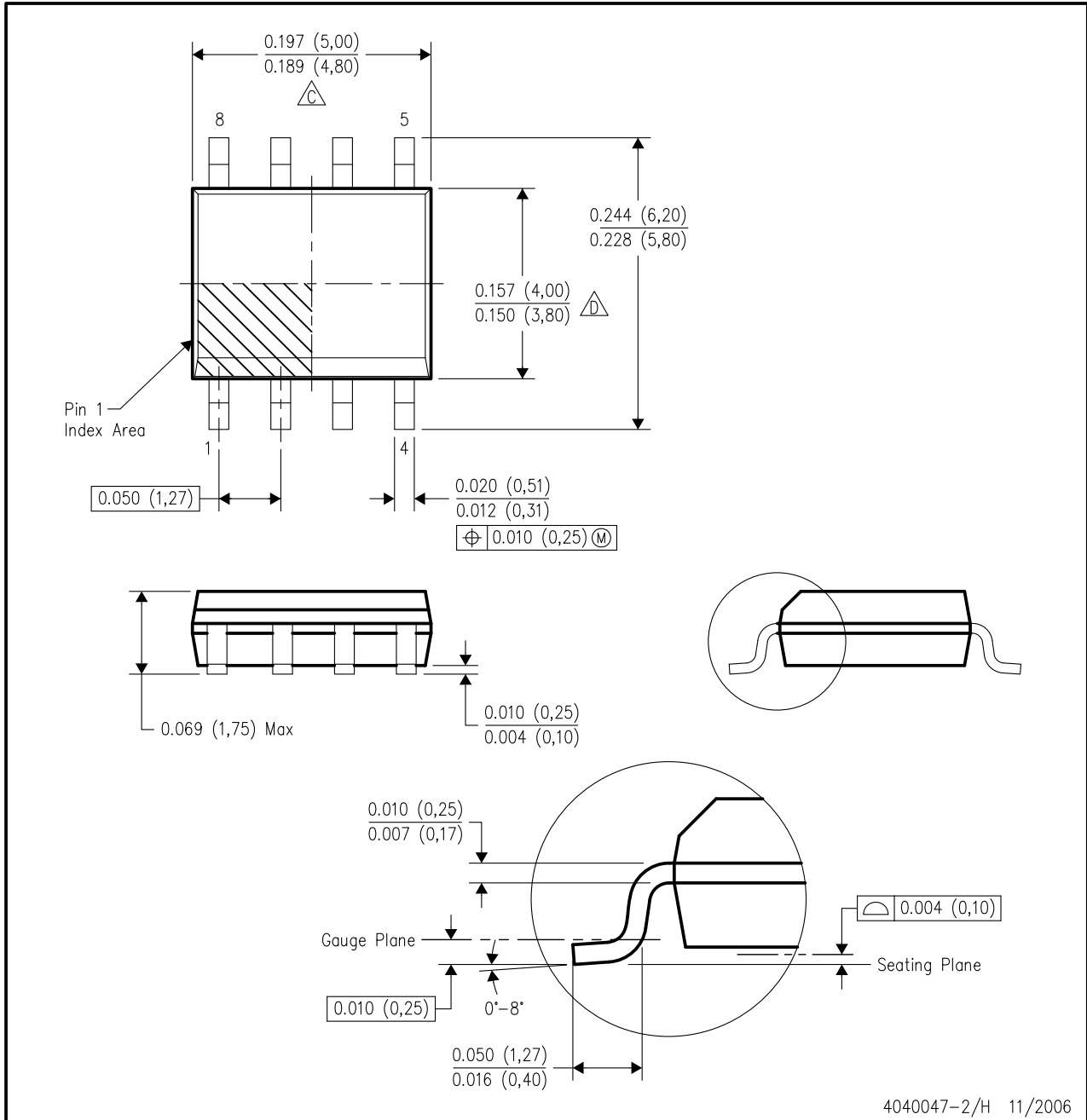




- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

MECHANICAL DATA

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

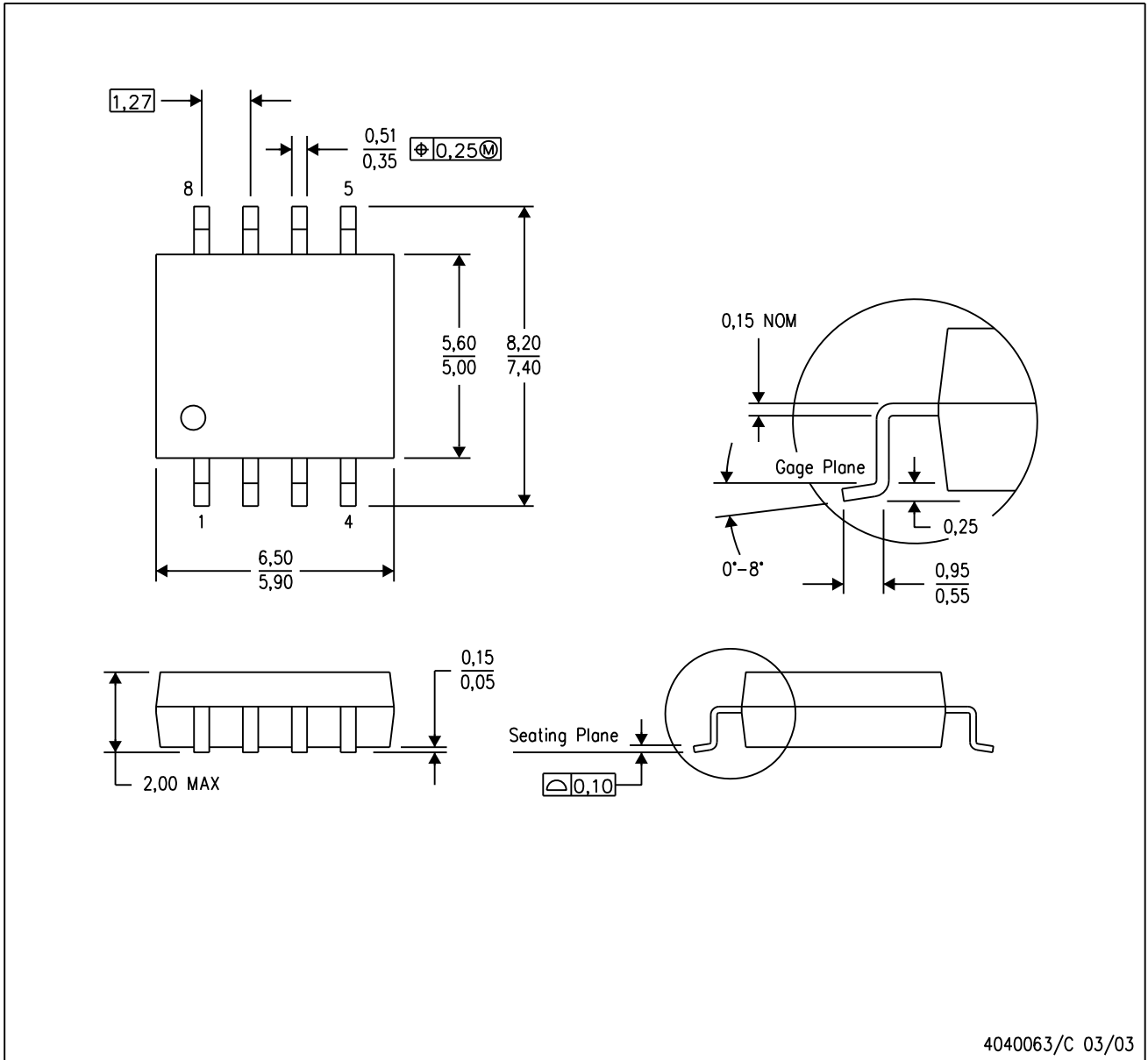


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 -  Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AA.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



4040063/C 03/03

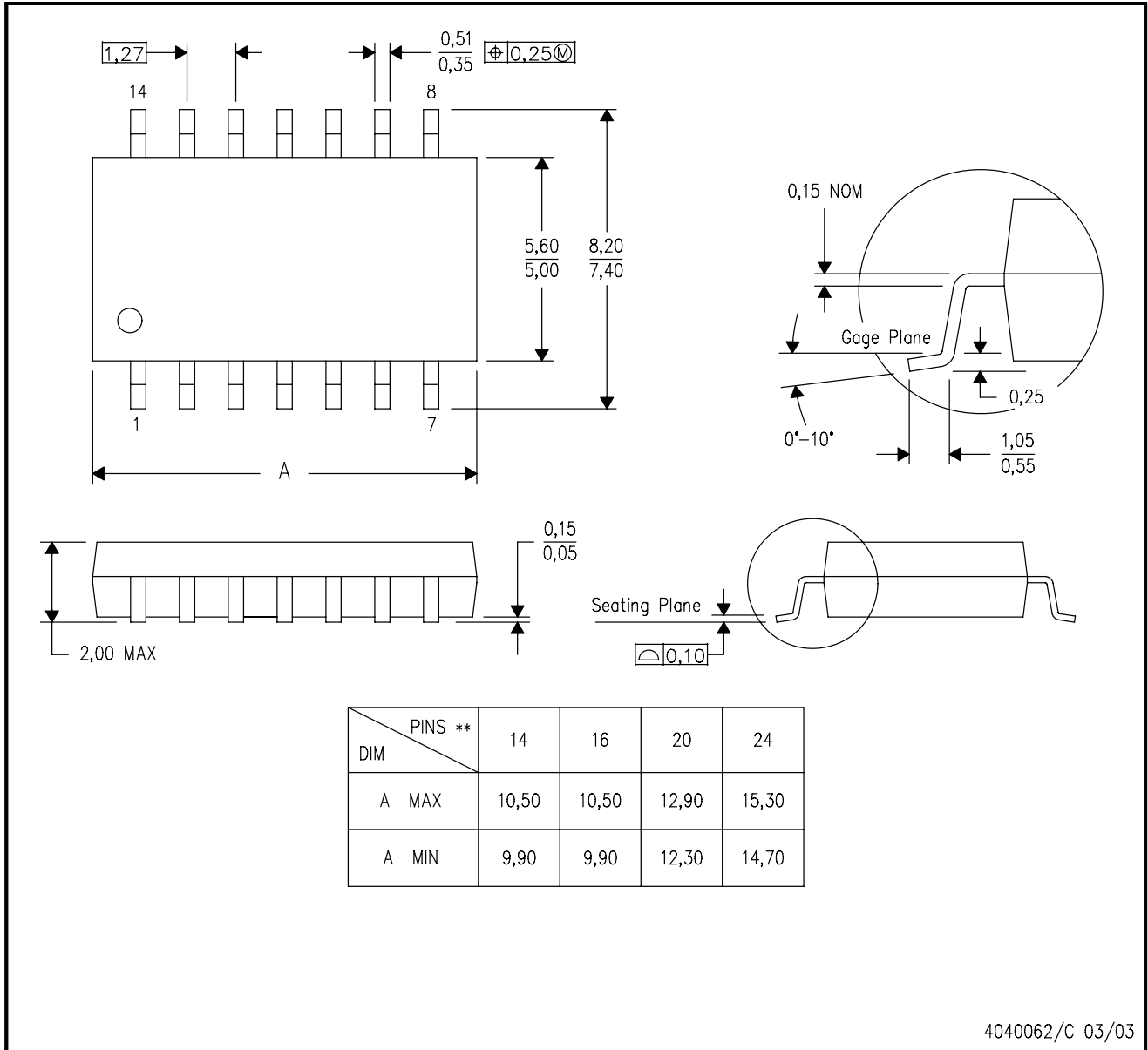
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

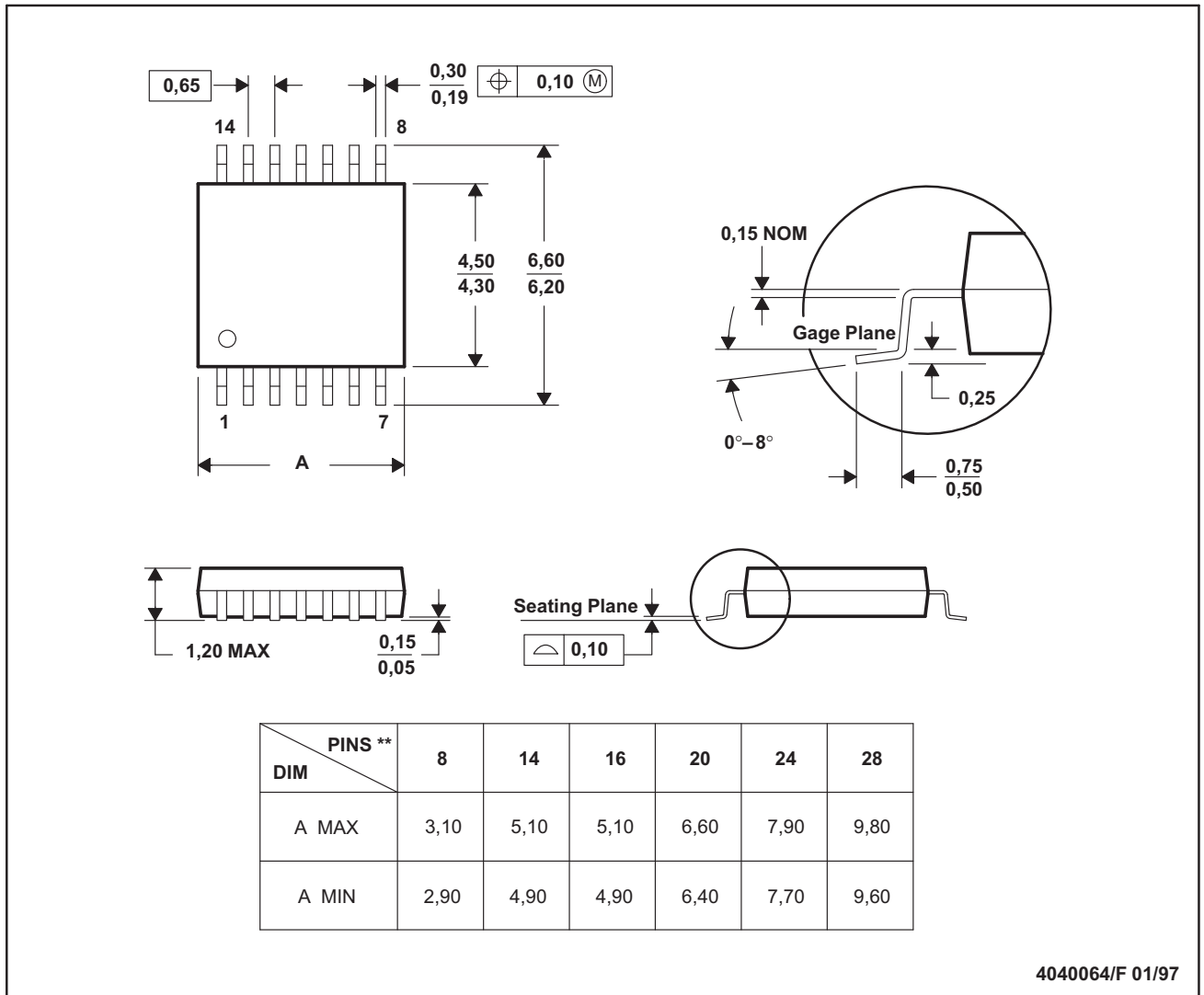


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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